

SOT584-1

plastic ball grid array package; 456 balls; body 35 x 35 x 1.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA456
Package type industry code	BGA456
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	26-6-2007

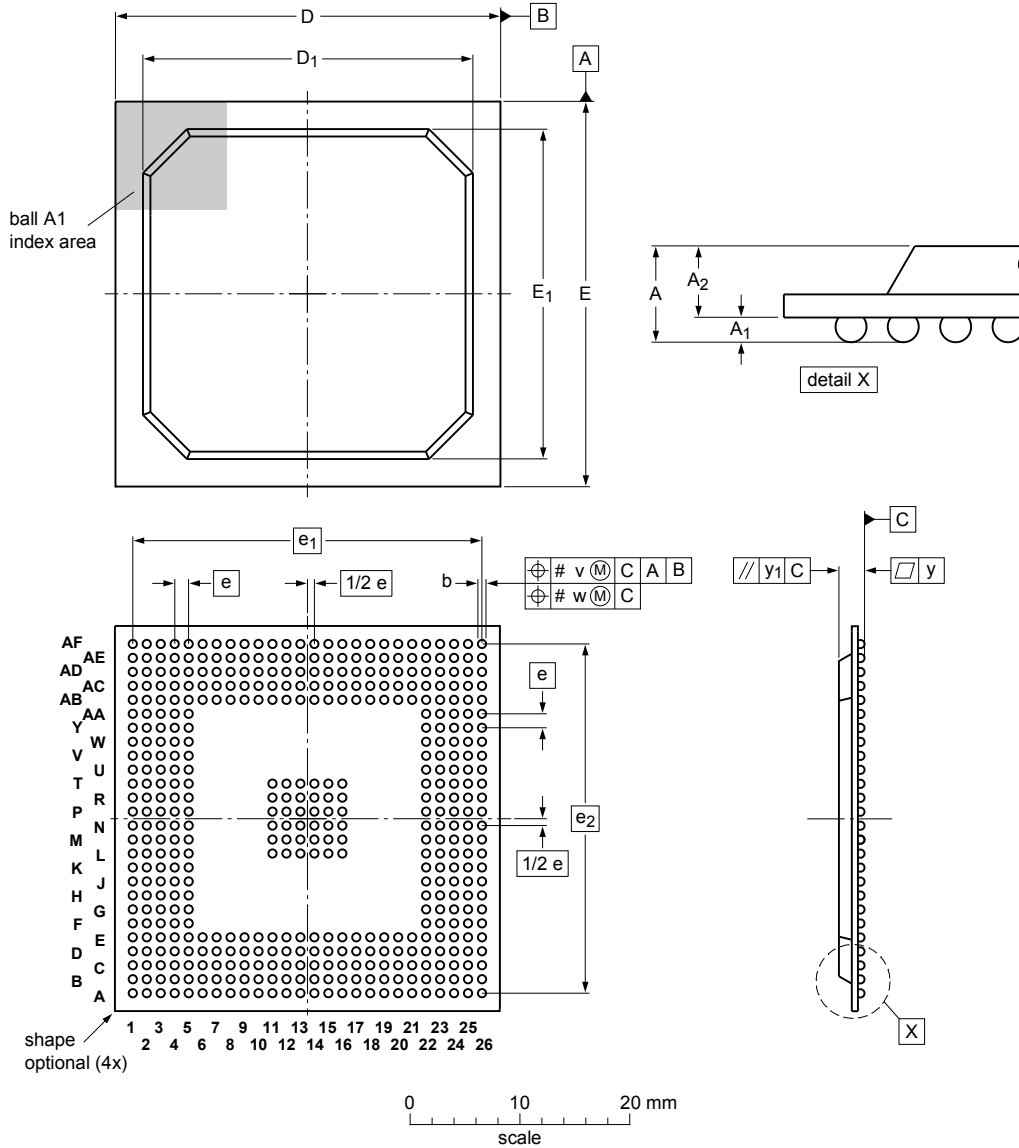
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.8	-	35	35.2	mm
E	package width	34.8	-	35	35.2	mm
A	seated height	[tbd]	-	2.55	2.55	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	456	-	



2. Package outline

BGA456: plastic ball grid array package; 456 balls; body 35 x 35 x 1.75 mm SOT584-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	v	w	y	y ₁
mm	2.55	0.7 0.5	1.85 1.60	0.9 0.6	35.2 34.8	30.70 29.95	35.2 34.8	30.70 29.95	1.27	31.75	31.75	0.3	0.15	0.2	0.35

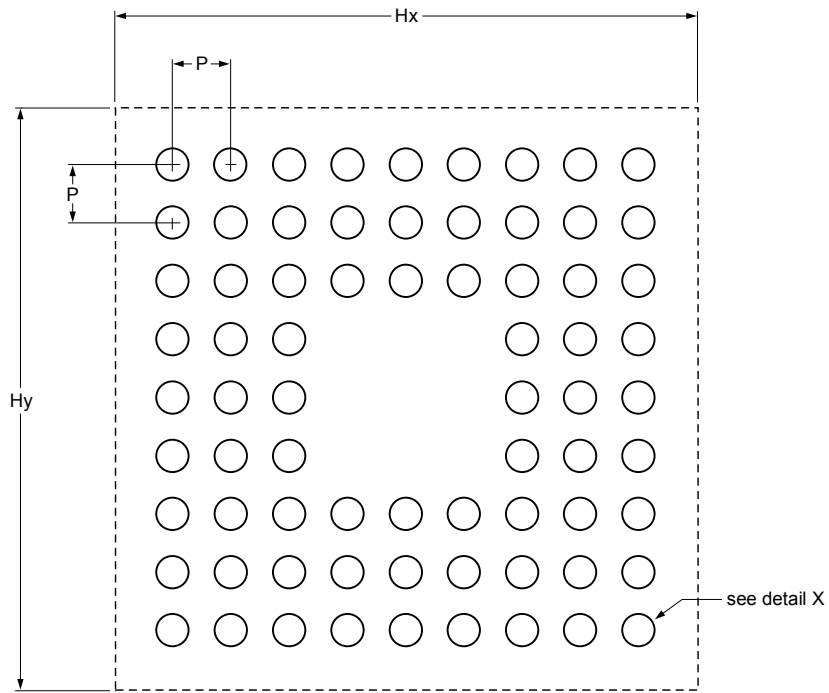
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT584-1	144E	MS-034	---			03-01-23 07-06-26

Fig. 1. Package outline BGA456 (SOT584-1)

3. Soldering

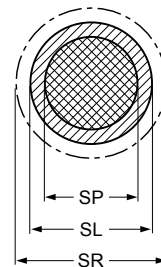
Footprint information for reflow soldering of BGA456 package

SOT584-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- solder resist



detail X

Dimensions in mm

P	SL	SP	SR	Hx	Hy
1.27	0.600	0.500	0.750	35.575	35.575

sot584-1_fr

Fig. 2. Reflow soldering footprint for BGA456 (SOT584-1)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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